

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER																																																																														
<div>Application Number : 10/680783</div> <div>Confirmation Number: 5859</div> <div>First Named Applicant: William Jones</div> <div>Attorney Docket Number:</div> <div>Art Unit:</div> <div>Examiner:</div> <div>Search string: (3681171 or 4827867 or 5009738 or 6221781 or 6306564 or 6497239 or 20030005948).pn</div> <div><p><u>Certification:</u> This Information Disclosure Statement was submitted under the following conditions, which satisfies the requirement under 37 CFR 1.97(e). The filer certified:</p><p>That each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.</p><p>US Patent Documents</p><p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p><table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>3681171</td><td>1972-08-01</td><td>Toku Hojo et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>4827867</td><td>1989-05-09</td><td>Takei et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>5009738</td><td>1991-04-23</td><td>Gruenwald et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>6221781</td><td>2001-04-24</td><td>Siefering et al.</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>5</td><td>6306564</td><td>2001-10-23</td><td>Mullee</td><td>B1</td><td></td><td></td></tr><tr><td></td><td>6</td><td>6497239</td><td>2002-12-24</td><td>Farmer et al.</td><td>B2</td><td></td><td></td></tr></tbody></table><p>US Published Applications</p><p>Note: Applicant is not required to submit a paper copy of cited US Published Applications</p><table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Pub. No.</th><th>Date</th><th>Applicant</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>20030005948</td><td>2003-01-09</td><td>Matsuno et al.</td><td>A1</td><td></td><td></td></tr></tbody></table><p>Signature</p></div>								init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	3681171	1972-08-01	Toku Hojo et al.					2	4827867	1989-05-09	Takei et al.					3	5009738	1991-04-23	Gruenwald et al.					4	6221781	2001-04-24	Siefering et al.	B1				5	6306564	2001-10-23	Mullee	B1				6	6497239	2002-12-24	Farmer et al.	B2			init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass		1	20030005948	2003-01-09	Matsuno et al.	A1		
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